

Mezalok Connector

(High Reliability Mezzanine Connector)



Mezalok Connector



Flexibility

Stack height available in 10, 12, 15 and 18 mm

114 position footprint compatible to XMC footprint and all dimensional constraints

Reliability

Mini-Box contact system provides 4 points of contact for high reliability

Stability

High temperature thermoplastic housings offer superior thermal stability and are low-outgassing

Compliant BGA board attach supports standard surface mount processing and excellent thermal stability

114 position footprint compatible to XMC footprint and all dimensional constraints

DESCRIPTION

Rugged surface mount mezzanine connector incorporating "quad-redundant" Mini-Box contact system for separable interface.

Available in 60, 114 and 320 positions with stack heights options 10, 12, 15 and 18 mm.

APPLICATIONS

Stacking or mezzanine applications for rugged embedded computing,

114 position supports VITA 61 XMC architecture as rugged, high speed alternative to VITA 42 XMC

ELECTRICAL

Supports data rates up to 10+ Gb/s

Pins can be allocated for single-ended or differential signal

MECHANICAL

500 mating cycles durability

Mating force: Maximum of 0.30 lbs per contact

-65°C to +125°C operating temperature

Shock and vibration per VITA 47 and 72 Halt Test requirements

LCP housings, white in color

MATERIALS

Pin Assembly:

Socket Assembly:	LCP housings, white in color
Socket Assembly.	LCP flousings, write in color
Contacts:	High Performance Copper Alloy, 30 and 50μ" Au in mating interface (Sn/Pb and SAC405 solder balls are available)

STANDARDS & SPECS

114 position is compliant to VITA 61

VITA 42 and VITA 61 are not intermateable, but are footprint and XMC architecture compatible

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Application specification:	114-132/9
Product specification:	108-2411
Test Report:	501-736

APPLICATION TOOLING

Product is installed via standard BGA surface mount processes.

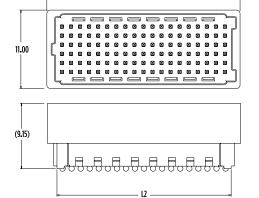


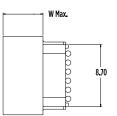


Mini-box contact

Position Size	Connector and Stack Height (mm)		50 Microinch Gold Mating Interface		30 Microinch Gold Mating Interface	
			Tin-Lead BGA	Lead Free BGA	Tin-Lead BGA	Lead Free BGA
Pin connector		2102079-1	2102079-2	2102079-3	2102079-4	
60	Socket Connector	10	2102080-1	2102080-2	2102080-5	2102080-6
		12	2102080-3	2102080-4	2102080-7	2102080-8
		18	2102080-9	1-2102080-0	1-2102080-1	1-2102080-2
	Pin Connector		2102060-1	2102060-2	2102060-3	2102060-4
	Socket Connector	10	2102061-1	2102061-2	2102061-5	2102061-6
114		12	2102061-3	2102061-4	2102061-7	2102061-8
		15	1-2102061-3	1-2102061-4	1-2102061-5	1-2102061-6
		18	2102061-9	1-2102061-0	1-2102061-1	1-2102061-2
320	Pin Connector		2102429-1	2102429-2	2102429-3	2102429-4
320	Socket Connector	10	2102430-1	2102430-2	2102430-5	2102430-6
		18	2102430-9	1-2102430-0	1-2102430-1	1-2102430-2

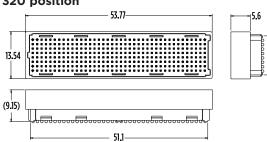
Pin — 60 position & 114 position



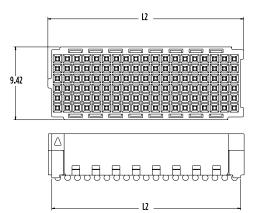


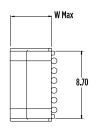
Pos.	LI	L2	W Max
60	15.67	13.00	5.60
114	27.10	24.43	5.60

320 position



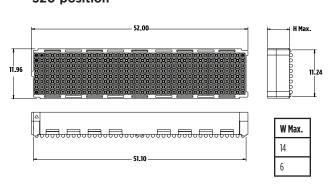
Socket - 60 position & 114 position





Pos.	LI	L2	W Max.
60	13.90	13.00	8, 6
114	25.33	24.43	14, 11, 8, 6

320 position



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FOR MORE INFORMATION

Technical Support

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